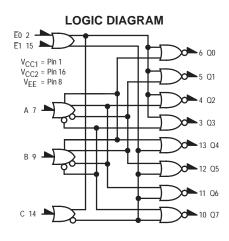
Binary to 1-8 Decoder (High)

The MC10H162 provides parallel decoding of a three bit binary word to one of eight lines. The MC10H162 is useful in high–speed multiplexer/demultiplexer applications.

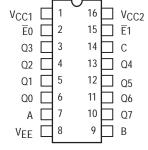
The MC10H162 is designed to decode a three bit input word to one of eight output lines. The MC10H162 output will be high when selected while all other output are low. The enable inputs, when either or both are high, force all outputs low.

The MC10H162 is a true parallel decoder. This eliminates unequal parallel path delay times found in other decoder designs. These devices are ideally suited for multiplexer/demultiplexer applications.

- Propagation Delay, 1.0 ns Typical
- Power Dissipation, 315 mW Typical (same as MECL 10K)
- Improved Noise Margin 150 mV (Over Operating Voltage and Temperature Range)
- Voltage Compensated
- MECL 10K-Compatible



DIP PIN ASSIGNMENT



Pin assignment is for Dual–in–Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).



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MARKING DIAGRAMS

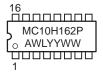


CDIP-16 L SUFFIX CASE 620





PDIP-16 P SUFFIX CASE 648





PLCC-20 FN SUFFIX CASE 775



A = Assembly Location

WL = Wafer Lot YY = Year

WW = Work Week

TRUTH TABLE

INPUTS				OUTPUTS								
E0	E ₁	С	В	Α	Q0	Q1	Q2	Q3	Q4	Q5	Q6	Q7
				LHLHLHL	H L L L L	LHLLL	LHLLL	L L H L L				3
H	X	H X	H X	H X	L	L	L	L	L	L	L	L
Х	Н	Х	Х	Х	L	L	L	L	L	L	L	L

ORDERING INFORMATION

Device	Package	Shipping
MC10H162L	CDIP-16	25 Units/Rail
MC10H162P	PDIP-16	25 Units/Rail
MC10H162FN	PLCC-20	46 Units/Rail

MAXIMUM RATINGS

Symbol	Characteristic	Rating	Unit
VEE	Power Supply (V _{CC} = 0)	-8.0 to 0	Vdc
VI	Input Voltage (V _{CC} = 0)	0 to VEE	Vdc
l _{out}	Output Current – Continuous – Surge	50 100	mA
TA	Operating Temperature Range	0 to +75	°C
T _{stg}	Storage Temperature Range – Plastic – Ceramic	−55 to +150 −55 to +165	°C °C

ELECTRICAL CHARACTERISTICS (VEE = -5.2 V ±5%) (See Note 1.)

	·							
		0 °		25°		75 °		
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
ΙΕ	Power Supply Current	_	84	_	76	-	84	mA
l _{inH}	Input Current High	_	465	_	275	-	275	μΑ
l _{inL}	Input Current Low	0.5	_	0.5	_	0.3	_	μΑ
Vон	High Output Voltage	-1.02	-0.84	-0.98	-0.81	-0.92	-0.735	Vdc
VOL	Low Output Voltage	-1.95	-1.63	-1.95	-1.63	-1.95	-1.60	Vdc
VIH	High Input Voltage	-1.17	-0.84	-1.13	-0.81	-1.07	-0.735	Vdc
VII	Low Input Voltage	-1.95	-1.48	-1.95	-1.48	-1.95	-1.45	Vdc

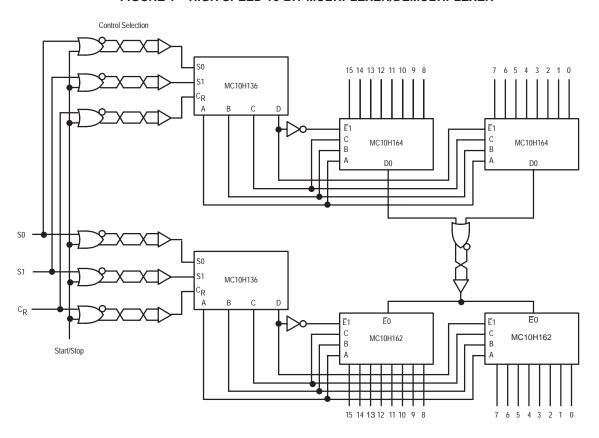
AC PARAMETERS

^t pd	Propagation Delay Pins 7, 9, 14 Only Pins 2, 15 Only	0.7 0.8	2.0 2.3	0.7 0.8	2.1 2.4	0.8 0.9	2.5 2.6	ns
t _r	Rise Time	0.6	1.8	0.6	1.9	0.6	2.0	ns
t _f	Fall Time	0.6	1.8	0.6	1.9	0.6	2.0	ns

^{1.} Each MECL 10H series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50–ohm resistor to –2.0 volts.

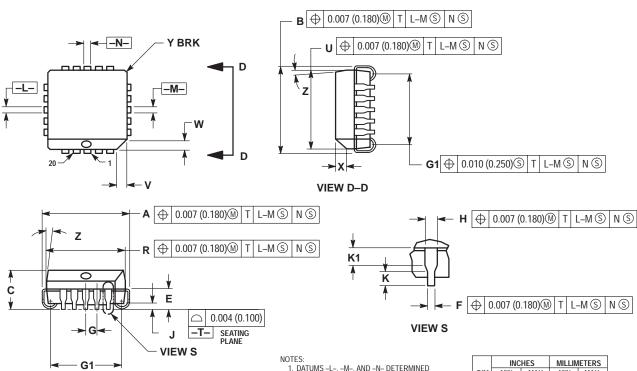
TYPICAL APPLICATIONS

FIGURE 1 – HIGH SPEED 16-BIT MULTIPLEXER/DEMULTIPLEXER



PACKAGE DIMENSIONS

PLCC-20 **FN SUFFIX** PLASTIC PLCC PACKAGE CASE 775-02 **ISSUE C**



⊕ 0.010 (0.250)⑤ T L-M ⑤ N ⑤

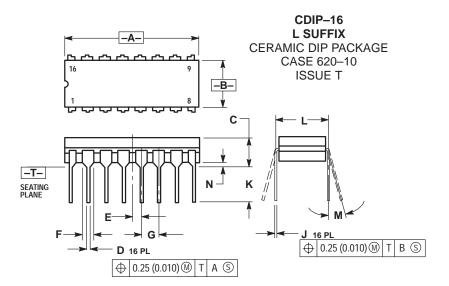
- WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
- 2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD.
- FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE. 4. DIMENSIONING AND TOLERANCING PER ANSI
- 4. DIMENSIONING AND TOLERANCING FER ANSI Y14.5M, 1982. 5. CONTROLLING DIMENSION: INCH. 6. THE PACKAGE TOP MAY BE SMALLER THAN THE
- PACKAGE BOTTOM BY UP TO 0.012 (0.300).
 DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP
- INCLUDING ANY MISMAICH BE I WEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.

 7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

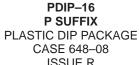
	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.385	0.395	9.78	10.03	
В	0.385	0.395	9.78	10.03	
С	0.165	0.180	4.20	4.57	
Ε	0.090	0.110	2.29	2.79	
F	0.013	0.019	0.33	0.48	
G	0.050	BSC	1.27 BSC		
Н	0.026	0.032	0.66	0.81	
J	0.020		0.51		
K	0.025		0.64		
R	0.350	0.356	8.89	9.04	
U	0.350	0.356	8.89	9.04	
V	0.042	0.048	1.07	1.21	
W	0.042	0.048	1.07	1.21	
Χ	0.042	0.056	1.07	1.42	
Υ		0.020		0.50	
Z	2°	10°	2 °	10 °	
G1	0.310	0.330	7.88	8.38	
K1	0.040		1.02		

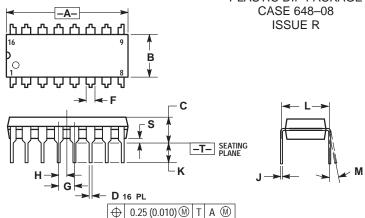
PACKAGE DIMENSIONS



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

	INC	HES	MILLIMETERS		
DIM	MIN	MIN MAX		MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015 0.020		0.39 0.50		
Ε	0.050	BSC	1.27 BSC		
F	0.055	0.055 0.065		1.65	
G	0.100	BSC	2.54 BSC		
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300	BSC	7.62 BSC		
M	0°	15°	0°	15°	
N	0.020	0.040	0.51	1.01	





- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: INCH.

 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.

 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

 5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIMETERS		
DIM	MIN MAX		MIN	MAX	
Α	0.740	0.740 0.770		19.55	
В	0.250 0.270		6.35	6.85	
С	0.145 0.175		3.69	4.44	
D	0.015 0.021		0.39	0.53	
F	0.040	0.040 0.70		1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110 0.130		2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10 °	0 °	10 °	
S	0.020	0.040	0.51	1.01	

Notes

Notes

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